

1

USB Type-C Analog Audio Switch With Protection Function

FEATURES

- Power Supply V_{CC}: 2.7V to 5.5V
- USB High-Speed (480Mbps) Switch
 - SDD₂₁ -3dB Bandwidth: 950MHz
 - 3Ω R_{ON} Typical
- Audio Switch
 - Negative Rail Capability: -3V to +3V
 - THD+N = -108dB; 1V_{RMS}, f = 20Hz to 20KHz, 32W Load
 - 0.9Ω R_{ON} Typical
- High Voltage Protection
 - 20V DC Tolerance on Connector Side Pins
 - Over Voltage Protection: V_{TH} = 5V(Typ.)
- OMTP and CTIA Pinout Support
- Support Audio Sense Path
- 25-Ball WLCSP Package (2.24mm x 2.28mm)

APPLICATIONS

- Mobile Phone
- Tablet
- Notebook PC
- Media Player

GENERAL DESCRIPTIONS

The ASW5480 is a high performance USB Type-C port Multimedia switch which supports analog audio headsets. ASW5480 allows the sharing of a common USB Type-C port to pass USB2.0 signal, analog audio, sideband use wires and analog microphone signal. ASW5480 also supports high voltage on SBU port and USB port on USB Type-C receptacle side.

BLOCK DIAGRAM

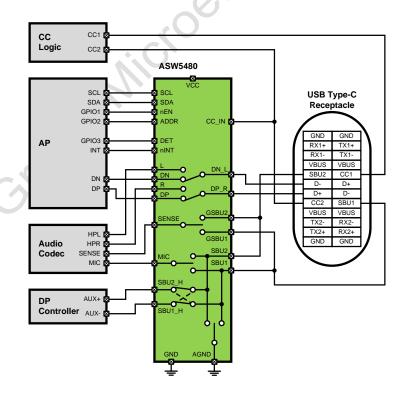


Figure 1, Block Diagram



PIN DIAGRAM

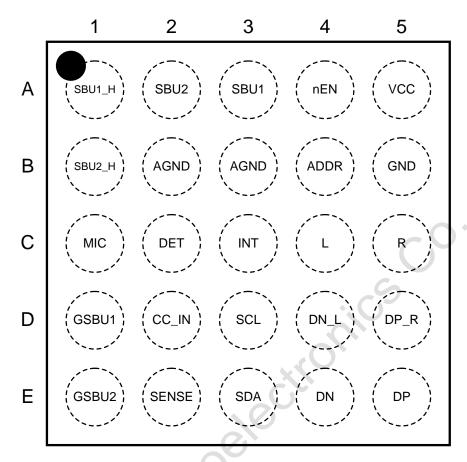


Figure 2, Pin Diagram (Top View)

PIN DESCRIPTIONS

	JOINII IIN			
No.	PIN No.	PIN NAME	TYPE	DESCRIPTIONS
1	A5	VCC	Power	Power Supply (2.7V to 5.5V)
2	B5	GND	Ground	Chip Ground
3	D5	DP_R	I/O	USB/Audio Common Connector
4	D4	DN_L	I/O	USB/Audio Common Connector
5	E5	DP	I/O	USB Data (Differential +)
6	E4	DN	I/O	USB Data (Differential -)
7	C5	R	I/O	Audio Right Channel
8	C4	Г	I/O	Audio Left Channel
9	A3	SBU1	I/O	Sideband Use Wire 1
10	A2	SBU2	I/O	Sideband Use Wire 2
11	C1	MIC	I/O	Microphone Signal
12	B2	AGND	Ground	Audio Signal Ground
13	B3	AGND	Ground	Audio Signal Ground
14	E2	SENSE	I/O	Audio Ground Reference Output
15	C3	nINT	0	I ² C Interrupt Output, Active Low (Open Drain)
16	D2	CC_IN		Audio Accessory Attachment Detection Input
17	D1	GSBU1	I/O	Audio Sense Path 1 to Headset Jack GND
18	E1	GSBU2	I/O	Audio Sense Path 2 to Headset Jack GND
19	C2	DET	0	Push-Pull Output. When CC_IN > 1.5V, DET is Low and
19	02	DET	U	CC_IN < 1.2V, DET is High
20	D3	SCL	I	I ² C Clock
21	E3	SDA	I/O	I ² C Data
22	B1	SBU2_H	I/O	Host Side Sideband Use Wire 2
23	A1	SBU1_H	I/O	Host Side Sideband Use Wire 1
24	A4	nEN	I	Chip Enable, Active Low, Internal Pull-Down by 470kΩ
25	B4	ADDR	1	I ² C Slave Address Pin



Absolute Maximum Ratings

Stress exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

SYMBOL	PARAMETER	MIN	MAX	UNIT
Vcc	Power Supply Voltage	-0.5	6.5	V
Vcc_in	CC_IN to GND	-0.5	20	V
V _{SW_C}	DP_R to GND, DN_L to GND	-3.5	20	V
V _{SW_USB}	DP to GND, DN to GND	-0.5	6.5	V
Vsw_audio	L to GND, R to GND	-3.5	6.5	V
V _{SBU/GSBU}	SBU1 to GND, SBU2 to GND, GSBU1 to GND, GSBU2 to GND	-0.5	20	V
V _{SBU_H}	SBU1_H to GND, SBU2_H to GND	-0.5	6.5	V
V _{I/O}	SENSE, MIC, DET, nINT to GND	-0.5	6.5	V
Vcntrl	Control Input Voltage (SDA, SCL, nEN, ADDR)	-0.5	6.5	V
Isw_audio	Switch I/O Current, Audio Path	-250	250	mA
I _{SW_USB}	Switch I/O Current, USB Path		100	mA
Isw_міс	Switch I/O Current, MIC to SBU1 or SBU2		50	mA
Isw_sbu	Switch I/O Current, SBUx to SBUx_H		50	mA
Isw_sense	Switch I/O Current, SENSE to GSBU1 or GSBU2		100	mA
Isw_agnd	Switch I/O Current, AGND to SBU1 or SBU2		500	mA
lıĸ	DC Input Diode Current	-50		mA
ECD	HBM Model (Connector Side and Power Pins: VCC, SBU1, SBU2, DP_R, DN_L, GSBU1, GSBU2, CC_IN)	4		KV
ESD	HBM Model (Host Side Pins: the rest pins)	2		KV
	CDM Model	1		KV
T _A	Absolute Maximum Operating Temperature	-40	+85	°C
T _{STG}	Storage Temperature	-65	+150	°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications.

SYMBOL	PARAMETER	MIN	MAX	UNIT
POWER				
Vcc	Supply Voltage	2.7	5.5	V
USB SWITCH				
V _{SW_USB}	DP to GND, DN to GND, DP_R to GND, DN_L to GND	0	3.6	V
AUDIO SWITCH	1			
V _{SW_AUDIO}	DP_R to GND, DN_L to GND, L to GND, R to GND	-3.6	3.6	V
MIC SWITCH				
V _{SBU_MIC}	SBU1 to GND, SBU2 to GND, MIC to GND	0	3.6	V
SENSE SWITCH	Ч			
V _{GSBU_SENSE}	GSBU1 to GND, GSBU2 to GND, SENSE to GND	0	3.6	V
SBU to SBUx_I	H SWITCH			
V _{GSBU}	SBU1 to GND, SBU2 to GND, SBU1_H to GND, SBU2_H to GND	0	3.6	V
CC_IN PIN				
Vcc_in	CC_IN to GND	0	5.5	V
CONTROL VOL	TAGE (nEN, SDA, SCL)			
ViH	Input Voltage High	1.3	Vcc	V
V_{IL}	Input Voltage Low		0.5	V
OPERATING TI	EMPERATURE			
TA	Ambient Operating Temperature	-40	+85	°C



DC CHARACTERISTICS

All typical values are at $V_{CC} = 3.3V$ and $T_A=25^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	POWER	MIN	TYP	MAX	UNIT
		USB Switches on, SBUx to SBUx_H switches on			39.5	65	μA
Icc	Supply Current	switch on and Audio GND			34.5	60	μA
	Ovices and Oversent	switch on			4.0	_	
I _{CCZ}	Quiescent Current COMMON PINS: DP_R, DN_I	nEN = L, 04H'b7 = 0			1.2	5	μA
USB/AUDIO	Off Leakage Current of		V _{CC} = 2.7 to			· ·	
loz	DP_R and DN_L Power-Off Leakage	DN_L, DP_R = -3V to 3.6V	5.5V	-3.0	0.7	3.0	μA
loff	Current of DP_R and DN_L	DN_L, DP_R = 0V to 3.6V	Power Off	-3.0	0.7	3.0	μA
V _{OV_TRIP}	Input OVP Lockout	Rising Edge	$V_{CC} = 2.7 \text{ to}$	4.5	5	5.3	V
Vov_HYS	Input OVP Hysteresis		5.5V		0.3		V
AUDIO SWIT		DN DD D 0\/ 4- 0.0\/	\/ 0.74-				
I _{ON}	On Leakage Current of Audio Switch	DN_L, DP_R = -3V to 3.0V, DP, DN, R, L = Floating	$V_{CC} = 2.7 \text{ to}$ 5.5V	-2.5	0.4	2.5	μΑ
I _{OFF}	Power-Off Leakage Current of L and R	L, R = 0V to 3V, DP_R, DN_L = Floating	Power Off	-1.0		1.0	μΑ
Ron_audio	Audio Switch On Resistance	$I_{SW} = 100$ mA, $V_{SW} = -3V$ to $3V$	Vcc = 2.7 to		0.9	2.1	Ω
RSHUNT	Pull-Down Resistor on R/L Pin When Audio Switch is OFF	Pull-Down Resistor on R/L Pin When Audio Switch is L = R = 3V		6	9.8	14	ΚΩ
USB SWITC	Н	_					
Ion	On Leakage Current of USB Switch	DN_L, DP_R = 0V to 3.0V, DP, DN, R, L = Floating	Vcc = 2.7 to	-3.0	0.5	3.0	μΑ
l _{OZ}	Off Leakage Current of DP and DN	DN, DP = 0V to 3.6V	5.5V	-3.0	0.8	3.0	μΑ
loff	Power-Off Leakage Current of DP and DN	DN, DP = 0V to 3.6V	Power OFF	-3.0		3.0	μΑ
Ron_usb	USB Switch On Resistance	Isw = 8mA, Vsw = 0.4V	$V_{CC} = 2.7 \text{ to}$ 5.5V		2.6	5.2	Ω
SENSE SWI	ТСН						
I _{ON}	Leakage Current of Sense Path	GSBUx = 0V to 1V, SENSE is floating		-2.0	0.18	2.0	μΑ
R _{ON_SENSE}	SENSE Switch On Resistance	I _{SW} = 100mA, V _{SW} = 1V	$V_{CC} = 2.7 \text{ to}$	0.2	0.7	1	Ω
	Off Leakage Current of SENSE	SENSE = 0V to 1V	5.5V	-2.0		2.0	μΑ
loz	Off Leakage Current of	GSBUx = 0V to 1V		-2.0		2.0	μΑ
	GSBUx	GSBUx = 1V to 3.6V		-3.0		3.0	μA
	Power-Off Leakage Current of SENSE	SENSE = 0V to 1V	D 0"	-2.0		2.0	μΑ
loff	Power-Off Leakage Current of GSBUx	GSBUx = 0V to 3.6V	Power Off	-3.0		3.0	μΑ
Vov_trip	Input OVP Lockout On GSBUx	Rising Edge	Vcc = 2.7 to	4.5	4.9	5.3	V
Vov_HYS	Input OVP Hysteresis of GSBUx		5.5V		0.3		V
SBUx PINS					1		
loz	Off Leakage Current of SBUx	SBUx = 0V to 3.6V	$V_{CC} = 2.7 \text{ to}$ 5.5V	-3.0		3.0	μA
I _{OFF}	Power-Off Leakage Current of SBUx	SBUx = 0V to 3.6V	Power OFF	-3.0		3.0	μA
V _{OV_TRIP}	Input OVP Lockout	Rising Edge	$V_{CC} = 2.7 \text{ to}$	4.5	4.9	5.3	V
Vov_Hys	Input OVP Hysteresis	3 3-	5.5V		0.3		V



DC CHARACTERISTICS (CONTINUED)
All typical values are at V_{CC} = 3.3V and T_A=25°C unless otherwise specified.

SYMBOL	PARAMETER	5°C unless otherwise specified. CONDITIONS	POWER	MIN	TYP	MAX	UNIT
MIC SWITCH	1						
Ion	On Leakage Current of MIC Switch	SBUx = 0V to 3.6V, MIC is floating	Vcc = 2.7 to	-3.0	0.38	3.0	μΑ
loz	Off Leakage Current of MIC	MIC = 0V to 3.6V	5.5V	-1.0		1.0	μΑ
loff	Power Off Leakage Current of MIC	MIC = 0V to 3.6V	Power Off	-1.0		1.0	μΑ
Ron_міс	MIC Switch On Resistance	Isw = 30 mA, V sw = 3.6 V	$V_{CC} = 2.7 \text{ to}$ 5.5V	1.7	3.0	3.9	Ω
SBUx_H SW							
Ion	On Leakage Current of SBUx_H Switch	SBUx = 0V to 3.6V, SBUx_H = Floating	V _{CC} = 2.7 to	-3.0	0.14	3.0	μA
loz	Off Leakage Current of SBUx_H	SBUx_H = 0V to 3.6V	5.5V	-1.0		1.0	μΑ
loff	Power-Off Leakage Current of SBUx_H	SBUx_H = 0V to 3.6V	Power Off	-1.0		1.0	μΑ
Ron_sbux_h	SBUx_H Switch On Resistance	$I_{SW} = 30$ mA, $V_{SW} = 0$ V to 3.6V	$V_{CC} = 2.7 \text{ to}$ 5.5V	1.5	2.7	3.5	Ω
AUDIO GRO	UND SWITCH (AGND to SBU	(x)					
RON_AGND	AGND Switch On Resistance	Isource = 100mA on SBUx	$V_{CC} = 2.7 \text{ to}$ 5.5V	30	57	90	mΩ
CC_IN PIN					,		
V _{TH_L}	Input Low Thershold		$V_{CC} = 2.7 \text{ to}$		1.2		V
V _{TH_H}	Input High Thershold	00 111 01/1 5 51/	5.5V		1.5	4.0	V
l _{IL} nINT, DET P	Input Leakage of CC_IN	CC_IN = 0V to 5.5V				1.0	μΑ
V _{OH}	Output High for DET	I _O = -2mA		1.5	1.8	2.0	V
Vol	Output Low for DET and nINT	$I_0 = 2mA$	$V_{CC} = 2.7 \text{ to}$ 5.5V	1.0	1.0	0.4	V
ADDR PIN	THINT						
VIH	Input Voltage High			0.9			V
VIL	Input Voltage Low		$V_{CC} = 2.7 \text{ to}$	0.0		0.7	V
IIL	Input Leakage of ADDR	ADDR = 0V to Vcc	5.5V	-1.0		1.0	μΑ
nEN PIN							
VIH	Input Voltage High		$V_{CC} = 2.7 \text{ to}$	0.9			V
V _{IH}	Input Voltage Low		5.5V			0.7	V
R _{PD}	Internal Pull-Down Resistor		5.5 v		470		ΚΩ
SDA, SCL PI							
V _{IL_I2C}	Input Voltage Low					0.4	V
V _{IH} _I2C	Input Voltage High			1.2			V
l _{12C}	Input Current of SDA and SCL Pins	SDA/SCL = 0V to 3.6V		-2.0		2.0	μA
V_{OL_SDA}	Output Voltage Low	$I_{OL} = 2mA$				0.3	V
I _{OL_SDA}	Output Current of Output Voltage Low	$V_{OL_SDA} = 0.2V$		10			mA



AC CHARACTERISTICS

All typical values are at $V_{CC} = 3.3V$ and $T_A=25^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	POWER	MIN	TYP	MAX	UNIT
AUDIO SWI	TCH						
	Audio Switch Turn On						
t _{delay}	Delay Time				40		μs
t _{rise}	Audio Switch Turn On Rising Time ⁽¹⁾	$DP_R = DN_L = 1V$, $R_L = 32\Omega$			200		μs
toff	Audio Switch Turn OFF Time				20		μs
XTALK	Cross Talk (Adjacent)	$f = 1KHz$, $R_L = 50\Omega$, $V_{SW} = 1V_{RMS}$			-100		dB
BW	-3dB Bandwidth	$R_L = 50\Omega$	$V_{CC} = 3.3V$		600	3/	MHz
Oirr	Off Isolation	$f = 1KHz$, $R_L = 50\Omega$, $C_L = 0pF$, $V_{SW} = 1V_{RMS}$			-100		dB
T.I.D. A.I	Total Harmonic Distortion +	$\begin{split} f &= 20 \text{Hz} \sim 20 \text{KHz}, \ \text{R}_{\text{L}} = 600 \Omega, \\ V_{\text{SW}} &= 2 V_{\text{RMS}} \\ f &= 20 \text{Hz} \sim 20 \text{KHz}, \ \text{R}_{\text{L}} = 32 \Omega, \end{split}$			-110		dB
THD+N	Noise Performance With A- Weighting Filter	$V_{SW} = 1V_{RMS}$ $f = 20Hz \sim 20KHz, R_L = 16\Omega,$			-108		dB
		$V_{SW} = 0.5V_{RMS}$			-104		dB
USB SWITC							
ton	USB Switch Turn On Time	DP_R = DN_L =1.5V,	•.()		60		μs
t _{OFF} BW	USB Switch Turn Off Time SDD ₂₁ -3dB Bandwidth	$R_L = 50\Omega$ $R_L = 50\Omega$			17 950		μs MHz
O _{IRR}	Off Isolation Between DP, DN and Common Node Pins	$f = 1 \text{KHz}, R_L = 50\Omega,$ $C_L = 0 \text{pF}, V_{SW} = 1 V_{RMS}$	Vcc = 3.3V		-100		dB
tovp	DP_R and DN_L Pins OVP Response Time	Vsw = 3.5V to 5.5V			1	1.5	μs
MIC/AUDIO	GROUND SWITCH						
t _{delay_MIC}	MIC Switch Turn On Delay Time	SBUx =1V, $R_L = 50\Omega$			40		μs
t _{rise_MIC}	MIC Switch Turn On Rising Time ⁽¹⁾	3B0X = 1 V, KL = 30Ω			250		μs
t _{delay_} AGND	AGND Switch Turn On Time	SBUx pulled up to 0.5V by	V _{CC} = 3.3V		100		μs
t _{rise_} AGND	AGND Switch Turn On Rising Time ⁽¹⁾	16Ω, AGND connect to GND	VCC = 3.3V		2200		μs
toff_mic	MIC Switch Turn OFF Time	SBUx =2.5V, $R_L = 50\Omega$			12		μs
toff_agnd	AGND Switch Turn OFF Time	SBUx: I _{SOURCE} = 10mA, Clamp to 2.5V			15		μs
BW	MIC Switch Bandwidth	$R_L = 50\Omega$			60		MHz
SBUx_H SV							
t _{ON}	SBUx_H Switch Turn On Time	SBUx_H =2.5V, R _L = 50Ω			60		μs
t _{OFF}	SBUx_H Switch Turn Off Time		Vcc = 3.3V		10		μs
BW	-3dB Bandwidth	$R_L = 50\Omega$	1		60		MHz
t _{OVP}	SBUx Pins OVP Response Time	V _{SW} = 3.5V to 5.5V			0.5	1	μs
SENSE SWI							
t _{delay}	SENSE Switch Turn On Delay Time				50		μs
t _{rise}	SENSE Switch Turn On Rising Time ⁽¹⁾	GSBUx =1V, $R_L = 50\Omega$			200		μs
t _{OFF}	SENSE Switch Turn Off Time		$V_{CC} = 3.3V$		12		μs
t _{OVP}	GSBUx Pins OVP Response Time	V _{SW} = 3.5V to 5.5V			0.7	1.5	μs
BW	-3dB Bandwidth	$R_L = 50\Omega$			150		MHz

⁽¹⁾ Turn On Timing can be controlled by I2C register.



AC CHARACTERISTICS (CONTINUED)

All typical values are at $V_{CC} = 3.3V$ and $T_A=25^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	POWER	MIN	TYP	MAX	UNIT
DET DELAY							
	DET Bospones Doloy Time	Transition from 0 to 1.8V	\/ 22\/		1		μs
t _{delay_} DET	DET Response Delay Time	Transition from 1.8 to 0V	$V_{CC} = 3.3V$		3		μs

I^2C SPECIFICATION (SCL, SDA) All typical values are at V_{CC} = 3.3V and T_A =25°C unless otherwise specified.

SYMBOL	PARAMETER	F/	AST MODE	
STIVIBUL	PARAWETER	MIN	MAX	UNIT
fscL	I ² C SCL Clock Frequency		400	KHz
thd;sta	Hold Time (repeated) START Condition	0.6		μs
t _{LOW}	Low Period of I ² C SCL Clock	1.3		μs
thigh	High Period of I ² C SCL Clock	0.6	* '	μs
tsu;sta	Set-up Time for Repeated START Condition	0.6		μs
thd;dat	Data Hold Time ⁽²⁾	0	0.9	μs
t _{SU;DAT}	Data Set-up Time ⁽³⁾	100		ns
t _r	Rise Time of I ² C SDA and I ² C SCL Signals ⁽³⁾	20 + 0.1C _b	300	ns
t _f	Fall Time of I ² C SDA and I ² C SCL Signals ⁽³⁾	20 + 0.1C _b	300	ns
tsu;sто	Set-up Time for STOP Condition	0.6		μs
t _{BUF}	Bus-Free Time Between STOP and START Conditions	1.3		μs
tsp	Pulse Width of Spikes that Must Be Suppressed by the Input Filter	0	50	ns

⁽²⁾Guaranteed by design, not production tested.

⁽³⁾ A fast-mode l^2C bus device can be used in a standard-mode l^2C bus system, but the requirement $t_{SU;DAT} \ge \pm 250$ ns must be met. This is automatically the case if the device does not stretch the LOW period of the l^2C SCL signal. If such a device does stretch the LOW period of the l^2C SCL signal, it must output the next data bit to the l^2C SDA line $t_{r_{max}} + t_{SU;DAT} = 1000 + 250 = 1250$ ns (according to the standard-mode l^2C bus specification) before the l^2C SCL line is released.

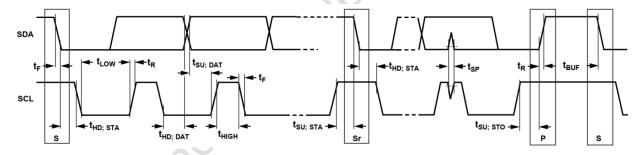


Figure 3, Definition of Timing for Full-Speed Mode Devices on the I²C Bus



CAPACITANCE

All typical values are at $V_{CC} = 3.3V$ and $T_A=25^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	POWER	T _A = -40°C to 85°C			
JJUL			· OTTER	MIN	TYP	MAX	UNI
Con_usb/audio	On Capacitance	f = 1MHz, 100mV _{PK-PK} ,			9		pF
	(Common Port) Off Capacitance	100mV DC Bias f = 1MHz, 100mV _{PK-PK} ,			-		•
Coff_usb/audio	(Common Port)	1 = TMHZ, TOUTTVPK-PK, 100mV DC Bias			7.5		pF
	Off Capacitance	f = 1MHz, 100mV _{PK-PK} ,					_
C_{OFF_USB}	(Non-Common Ports)	100mV DC Bias			3		pF
Ca., an., a.,	On Capacitance	f = 1MHz, 100mV _{PK-PK} ,			55		рF
Con_sense_sw	(Common Port)	100mV DC Bias			55	<u> </u>	þi
Coff_sense_sw	Off Capacitance	$f = 1MHz$, $100mV_{PK-PK}$,			88		pF
	(Common Port) On Capacitance	100mV DC Bias f = 1MHz, 100mV _{PK-PK} ,	Vcc = 3.3V				•
Con_mic_sw	(Common Port)	100mV DC Bias			170		рŀ
	Off Capacitance	f = 1MHz, 100mV _{PK-PK} ,					_
Coff_mic_sw	(Common Port)	100mV DC Bias			10		рF
Courtous	On Capacitance	f = 1MHz, 100mV _{PK-PK} ,			125		рF
Con_agnd_sw	(Common Port)	100mV DC Bias			125		þr
Con_sbux_h_sw	On Capacitance	$f = 1MHz$, $100mV_{PK-PK}$,	Co		160		рF
	(Common Port)	100mV DC Bias					1
CCNTRL	Control Input Pin Capacitance (nEN Pin)	f = 1MHz, 100mV _{PK-PK} , 100mV DC Bias			3		pl
		croelecti					
		Nicroelecia					
	Ckaryo	Nicroelecti					
	Citaing	Microelecti					
	Ckarly	Nickoelecti					



APPLOCATION INFORMATION

Over-Voltage Protection

The ASW5480 features Over-Voltage Protection (OVP) on receptacle side pins that switch off the internal signal routing path if the input voltage exceeds the OVP threshold. If OVP is occurred, interrupt signal can be send by nINT signal and FLAG data will provide information that which pin had OVP event.

Headset Detection

The ASW5480 integrates headset unplug detection function by detecting the CC_IN voltage. The function is always active when device is enabling⁽⁴⁾. DET will be high when CC_IN is Low (CC_IN < 1.2V). When CC_IN is High (CC_IN > 1.5V), DET will be released to low.

	ASW5480 Disable	ASW5480 Enable
$CC_IN < V_{TH_L} = 1.2V$	DET = 0	DET = 1
$CC_{IN} > V_{TH_{H}} = 1.5V$	DET = 0	DET = 0

⁽⁴⁾ DET pin is in Push/Pull Configuration as default. If you don't use this detection function, leave it floating.

MIC Switch Auto-Off Function

The function is active during control bit 0x12h bit[2] = 1. When CC_IN is high (CC_IN > 1.5V) and L, R, Audio ground switches are under on status, MIC switch will be off and receptacle side pin will be connected to ground for 50μ s first. Then it shows High-Z status under MIC switch is set on status.

<u>Audio Ground Detection and Configuration</u>

The function is active during control bit 0x12h bit[0] = 1 and R, L, AGND switches are set to be on status. For Type-C interface analog headset, the audio ground could be SBU1 pin or SBU2 pin. The function will provide autonomous detection and configuration to route MIC and audio ground signal accordingly.

During detection and configuration, the L, R, SENSE, MIC and Audio ground switch will be off. After detection and configuration, L and R switches will turn on according to switch configuration and timing setting. MIC, SENSE and Audio ground will turn on according to detection results and timing control setting.

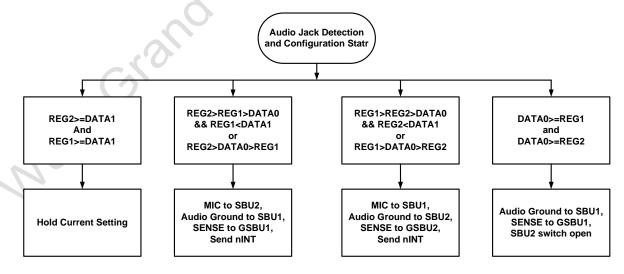


Figure 4, Audio Ground Detection and Configuration



Resistance Detection

The function is active during control bit 0x12h bit[1] = 1. It will monitor the resistance between receptacle side pins and ground. During resistance detection, the switch which is monitored will be off. The detection result will be saved in the resistance flag register. The measurement could be from $1K\Omega$ to $2.56M\Omega$ which is controlled by internal register. The detection interval can be set at 100ms, 1s or 10s by register 0x16h.

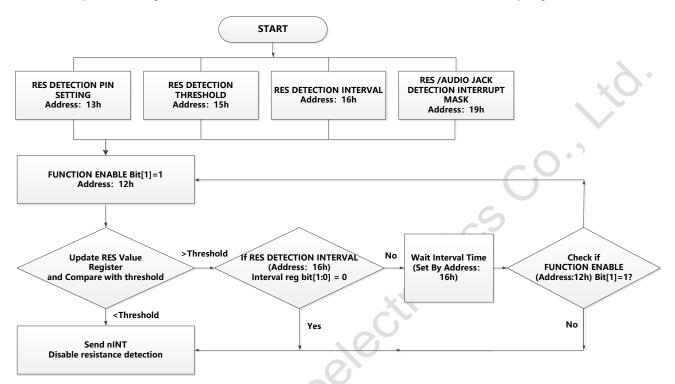


Figure 5, Resistance Detection

Manual Switch Control

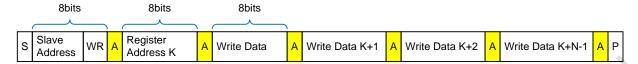
The function is active during control bit 0x12h bit[4] = 1 and 0x04h = FF. it will provide manual control for device. During this configuration, ADDR and nINT pins will be set as logic control input.

Power	nEN	ADDR	nINT	SENSE Switch	Headset Detection	USB Switch	Audio Switch	MIC/ AGND Switch	SBU Bypass Switch
OFF	Х	X	Х	OFF	OFF	OFF	OFF	OFF	OFF
ON	Н	X	X	OFF	OFF	OFF	OFF	OFF	OFF
ON	L	0	0	OFF	OFF	ON: DP_R to DP, DN_L to DN	OFF	OFF	ON: SBU1 to SBU1_H, SBU2 to SBU2_H
ON	_	0	1	OFF	OFF	ON: DP_R to DP, DN_L to DN	OFF	OFF	ON: SBU1 to SBU2_H, SBU2 to SBU1_H
ON) L	1	0	ON: GSBU2 to SENSE	ON	OFF	ON: DP_R to R, DN_L to L	ON: SBU1 to MIC, SBU2 to AGND	OFF
ON	L	1	1	ON: GSBU1 to SENSE	ON	OFF	ON: DP_R to R, DN_L to L	ON: SBU2 to MIC, SBU1 to AGND	OFF



12C INTERFACE

The ASW5480 includes a full I²C slave controller. The I2C slave fully complies with I²C specification version 2.1 requirements. This block is designed for fast mode, 400-KHz signals. Examples of an I²C write and read sequence are shown in below figures respectively.



NOTE: Single Byte Read is initiated by Master with P immediately following first data byte.

Figure 6, I²C Write Example



Register address to read specified

Single or Multi byte read executed from current register location (Single byte read is initiated by Master with NA immediately following first data byte)

NOTE: If Register is not specified Master will begin read from current register. In this case only sequence showing in Red bracket is needed.

From Master to Slave S Start Condition NA Not Acknowledge (SDA High) RD Read = 1
From Slave to Master A Acknowledge (SDA Low) WR Write = 0 P Stop Condition

Figure 7, I²C Read Example

Table 1. I²C Slave Address

Mn4; Ckaiu

ADDR	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
ADDR = L	1	0	0	0	0	1	0	R/W
ADDR = H	1	0	0	0	0	1	1	R/W



REGISTER MAPS

ADDR	Register Name	Туре	Reset Value	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
00H	Device ID	R	0x09	0	0	0	0	1	0	0	1
01H	OVP Interrupt Mask	R/W	0x00	Reserved	Mask OVP Interrupt	Mask OVP /DP_R	Mask OVP /DN_L	Mask OVP /SBU1	Mask OVP /SBU2	Mask OVP /GSBU1	Mask OVP /GSBU2
02H	OVP Interrupt flag	R/C	0x00	Rese	erved	DP_R	DN_L	SBU1	SBU2	GSBU1	GSBU2
03H	OVP Status	R	0x00	Rese	erved	OVP /DP_R	OVP /DN_L	OVP /SBU1	OVP /SBU2	OVP /GSBU1	OVP /GSBU2
04H	Switch settings Enable	R/W	0x98	Device Control	SBU1_H to SBUx	SBU2_H to SBUx	DN_L to DN or L	DP_R to DP or R	Sense to GSBUx	MIC to SBUx	Audio Ground to SBUx
05H	Switch Select	R/W	0x18	Reserved	SBU1_H to SBUx	SBU2_H to SBUx	DN_L to DN or L	DP_R to DP or R	Sense to GSBUx	MIC to SBUx	Audio Ground to SBUx
06H	Switch Status0	R	0x05	Rese	erved	Sense Sw	itch Status	DP_R Sv	vitch Status	DN_L Sw	itch Status
07H	Switch Status1	R	0x00	Rese	erved	SBI	J2 Switch St	tatus	SE	BU1 Switch St	atus
08H	Audio switch left channel turn on control	R/W	0x01			Audio Swi	ch Left Cha	nnel Slow C	ontrol [7:0]		
09H	Audio switch right channel turn on control	R/W	0x01			Audio Swite	ch Right Cha	annel Slow (Control [7:0]		
0AH	MIC switch turn on control	R/W	0x01			MIC Switc	h Right Cha	nnel Slow C	ontrol [7:0]		
0BH	Sense switch turn on control	R/W	0x01			SENSE Swi	tch Right Ch	annel Slow	Control [7:0]]	
0CH	Audio Ground Switch turn on control	R/W	0x01		Au	dio Ground S	Switch Right	Channel Sl	ow Control [7:0]	
0DH	Timing Delay between R switch enable and L switch enable	R/W	0x00		Timing Delay	y Between R	Switch Ena	ble and L Sv	witch Enable	e Control [7:0]	
0EH	Timing Delay between MIC switch enable and L switch enable	R/W	0x00		iming Delay	Between MI	C Switch En	able and L S	Switch Enab	le Control [7:0	סן
0FH	Timing Delay between Sense switch enable and L switch enable	R/W	0x00	Tiı	ming Delay E	Between Sen	se Switch E	nable and L	Switch Enal	ble Control [7	:0]
10H	Timing Delay between Audio Ground switch enable and L switch enable	R/W	0x00	Timing Delay Between Audio Ground Switch Enable and L Switch Enable Control [7:0]							
11H	Audio accessory status	R	0x02			Rese	ved			CC_IN	DET
12H	Function Enable	R/W	0x08	Reserved	DET I/O Control	RES	GPIO Control	Slow turn-on Control	MIC Auto Control	RES detection: auto clear	Audio jack detection: auto clear
13H	RES detection pin setting	R/W	0x00			Reserved			Detec	ction pin selec	ct [2:0]



REGISTER MAPS(CONTINUED)

ADDR	Register Name	Туре	Reset Value	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
14H	RES detection value	R	0xFF		R detection value [7:0]										
15H	RES detection interrupt threshold	R/W	0x16		R detection interrupt resistance threshold [7:0]										
16H	RES detection interval	R/W	0x00		Reserved Detection interval [1:0]						Reserved				
17H	Audio jack status	RO	0x01		4-pole, 4-pole, SBU2 SBU1 MIC MIC					3-pole	No audio				
18H	Detection interrupt	R/C	0x00		Reserved Audio detection done					RES detection occurred	RES detection done				
19H	Detection interrupt Mask	R/W	0x00		Reserved Audio detection done mask					RES detection occurred mask	RES detection done mask				
1AH	Audio detection REG1	RO	0xFF		Audio detection value REG1 [7:0]										
1BH	Audio detection REG2	RO	0xFF			Au	dio detection	value REG2	[7:0]						
1CH	MIC threshold DATA0	R/W	0x20	MIC Threshold value DATA0 [7:0]											
1DH	MIC threshold DATA1	R/W	0xFF	MIC Threshold value DATA1 [7:0]											
1EH	I2C reset	W/C	0x00	Reserved I2C reset						I2C reset					
1FH	Current source setting	R/W	0x07		Res	erved			Current Source	ce Setting [3:	0]				

Table 2, DEVICE ID

(Register 0x00h, Reset Value: 0x09, Type: Read)

I	BITS	NAME	SIZE	DESCRIPTION
I	7:6	Vendor ID	2	Vendor ID
I	5:3	Version ID	3	Device Version ID
I	2:0	Revision ID	3	Revision History ID

Table 3, OVP INTERRUPT MASK

(Register 0x01h, Reset Value: 0x00, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7	Reserved	1	Do not use
6	OVP Interrupt mask control	1	OVP Interrupt function enable/disable 0: controlled by [5:0] bit 1: Mask all connector side pins OVP interrupt
5	DP_R OVP Interrupt mask control	1	0: Do not mask OVP interrupt 1: Mask OVP interrupt
4	DN_L OVP Interrupt mask control	1	O: Do not mask OVP interrupt Mask OVP interrupt
3	SBU1 OVP Interrupt mask control	1	O: Do not mask OVP interrupt Historian interrupt
2	SBU2 OVP Interrupt mask control	1	O: Do not mask OVP interrupt Mask OVP interrupt
1	GSBU1 OVP Interrupt mask control	1	O: Do not mask OVP interrupt Mask OVP interrupt
0	GSBU2 OVP Interrupt mask control	1	O: Do not mask OVP interrupt Mask OVP interrupt



Table 4, OVP INTERRUPT FLAG

(Register 0x02h, Reset Value: 0x00, Type: Read Clear)

BITS	NAME	SIZE	DESCRIPTION
7:6	Reserved	2	Do not use
5	DP_R OVP	1	0: OVP event has not occurred 1: OVP event has occurred
4	DN_L OVP	1	0: OVP event has not occurred 1: OVP event has occurred
3	SBU1 OVP	1	0: OVP event has not occurred 1: OVP event has occurred
2	SBU2 OVP	1	0: OVP event has not occurred 1: OVP event has occurred
1	GSBU1 OVP	1	0: OVP event has not occurred 1: OVP event has occurred
0	GSBU2 OVP	1	0: OVP event has not occurred 1: OVP event has occurred

Table 5, OVP STATUS

(Register 0x03h, Reset Value: 0x00, Type: Read)

(Negister oxosii, Neset value, oxoo, Type, Neau)			
BITS	NAME	SIZE	DESCRIPTION
7:6	Reserved	2	Do not use
5	OVP on DP_R Pin	1	0: OVP event has not occurred 1: OVP event has occurred
4	OVP on DN_L Pin	1	OVP event has not occurred OVP event has occurred
3	OVP on SBU1 Pin	1	0: OVP event has not occurred 1: OVP event has occurred
2	OVP on SBU2 Pin	1	0: OVP event has not occurred 1: OVP event has occurred
1	OVP on GSBU1 Pin	1	0: OVP event has not occurred 1: OVP event has occurred
0	OVP on GSBU2 Pin	1	0: OVP event has not occurred 1: OVP event has occurred

Table 6, SWITCHING SETTING ENABLE

(Register 0x04h, Reset Value: 0x98, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7	Device Enable	1	0: Device Disable; L, R are pulled-down by 10kΩ and other switch nodes will be High-Z for positive input.1: Device Enable.
6	SBU1_H to SBUx switches	1	O: Switch Disable; SBU1_H will be High-Z for positive input; 1: Switch Enable.
5	SBU2_H to SBUx switches	1	O: Switch Disable; SBU2_H will be High-Z for positive input; 1: Switch Enable.
4	DN_L to DN or L switches	1	0: Switch Disable; DN_L, DN will be High-Z for positive input and L is pulled-down by 10kΩ. 1: Switch Enable.
3	DP_R to DP or R switches	1	 0: Switch Disable; DP_R, DP will be High-Z for positive input and R is pulled-down by 10kΩ. 1: Switch Enable.
2	Sense to GSBUx switches	1	O: Switch Disable; Sense, GSBU1 and GSBU2 will be High-Z for positive input. 1: Switch Enable.
1	MIC to SBUx switches	1	0: Switch Disable; MIC will be High-Z for positive input. 1: Switch Enable.
0	AGND to SBUx switches	1	O: Switch Disable; AGND will be High-Z for positive input. 1: Switch Enable.



Table 7, SWITCH SELECT

(Register 0x05h, Reset Value: 0x18, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7	Reserved	1	Do not use
6	SBU1_H switches	1	0: SBU1_H to SBU1 switch ON 1: SBU1_H to SBU2 switch ON
5	SBU2_H switches	1	0: SBU2_H to SBU2 switch ON 1: SBU2_H to SBU1 switch ON
4	DN_L or DN or L switches	1	0: DN_L to L switch ON 1: DN_L to DN switch ON
3	DP_R or DP or R switches	1	0: DP_R to R switch ON 1: DP_R to DP switch ON
2	Sense to GSBUx switches	1	0: Sense to GSBU1 switch ON 1: Sense to GSBU2 switch ON
1	MIC to SBUx switches	1	0: MIC to SBU2 switch ON 1: MIC to SBU1 switch ON
0	AGND to SBUx switches	1	0: AGND to SBU1 switch ON 1: AGND to SBU2 switch ON

Table 8, SWITCH STATUS0

(Register 0x06h, Reset Value: 0x05, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:6	Reserved	2	Do not use
5:4	Sense Switch Status	2	00: Sense switch is Open/Not Connected 01: Sense connected to GSBU1 10: Sense connected to GSBU2 11: Not Valid
3:2	DP_R Switch Status	2	00: DP_R switch is Open/Not Connected 01: DP_R connected to DP 10: DP_R connected to R 11: Not Valid
1:0	DN_L Switch Status	2	00: DN_L switch is Open/Not Connected 01: DN_L connected to DN 10: DN_L connected to L 11: Not Valid

Table 9, SWITCH STATUS1

(Register 0x07h, Reset Value: 0x00, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:6	Reserved	2	Do not use
5:3	SBU2 SwitchStatus	3	000: SBU2 switch is Open/Not Connected 001: SBU2 connected to MIC 010: SBU2 connected to AGND 011: SBU2 connected to SBU1_H 100: SBU2 connected to SBU2_H 101: SBU2 connected both SBU1_H and SBU2_H 110111: Do not use
2:0	SBU1 SwitchStatus	3	000: SBU1 switch is Open/Not Connected 001: SBU1 connected to MIC 010: SBU1 connected to AGND 011: SBU1 connected to SBU1_H 100: SBU1 connected to SBU2_H 101: SBU1 connected both SBU1_H and SBU2_H 110111: Do not use

Table 10, AUDIO SWITCH LEFT CHANNEL SLOW TURN-ON

(Register 0x08h, Reset Value: 0x01, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
	Switch turn on rising time setting	8	11111111: 25600µs
7:0			 00000001: 200μs
			00000000: 100μs



Table 11, AUDIO SWITCH RIGHT CHANNEL SLOW TURN-ON

(Register 0x09h, Reset Value: 0x01, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:0	Switch turn on rising time setting	8	11111111: 25600μs 00000001: 200μs 00000000: 100μs

Table 12, MIC SWITCH SLOW TURN-ON

(Register 0x0Ah, Reset Value: 0x01, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
			11111111: 25700µs
7:0	Switch turn on rising time setting	8	00000010: 350μs
			00000001: 250µs
			0000000: Not Valid

Table 13, SENSE SWITCH SLOW TURN-ON

(Register 0x0Bh, Reset Value: 0x01, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:0	Switch turn on rising time setting	8	11111111: 25600μs 00000001: 200μs 00000000: 100μs

Table 14, AUDIO GROUND SWITCH SLOW TURN-ON

(Register 0x0Ch, Reset Value: 0x01, Type: Read/Write)

(110910101			
BITS	NAME	SIZE	DESCRIPTION
			11111111: 179000µs
7:0	Switch turn on rising time setting 8	0	
7.0		0	0000001: 1400µs
			00000000: 700µs

Table 15, TIMING DELAY BETWEEN R SWITCH ENABLE AND L SWITCH ENABLE

(Register 0x0Dh, Reset Value: 0x00, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
			11111111: 25500µs
			11111110: 25400µs
7:0	Delay timing setting	8	
			00000001: 100μs
			00000000: 0µs

Table 16, TIMING DELAY BETWEEN MIC SWITCH ENABLE AND L SWITCH ENABLE

(Register 0x0Eh, Reset Value: 0x00, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
			11111111: 25500µs
			11111110: 25400µs
7:0	Delay timing setting	8	
. 13			00000001: 100µs
			00000000: 0μs

Table 17, TIMING DELAY BETWEEN SENSE SWITCH ENABLE AND L SWITCH ENABLE

(Register 0x0Fh. Reset Value: 0x00. Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
			11111111: 25500µs
			11111110: 25400µs
7:0	Delay timing setting	8	
			00000001: 100μs
			00000000: 0μs



Table 18, TIMING DELAY BETWEEN AUDIO GROUND SWITCH ENABLE AND L SWITCH ENABLE

(Register 0x10h, Reset Value: 0x00, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
			11111111: 25500µs 11111110: 25400µs
7:0	Delay timing setting	8	
			00000001: 100μs
			00000000: 0µs

Table 19, AUDIO ACCESSORY STATUS

(Register 0x11h, Reset Value: 0x02, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:2	Reserved	6	Do not use
1	CC_IN	1	0: CC_IN < 1.2V 1: CC_IN > 1.5V
0	DET	1	0: DET output is Low 1: DET output is High

Table 20, FUNCTION ENABLE

(Register 0x12h, Reset Value: 0x08, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7	Reserved	1	Do not use
6	DET I/O Control	1	DET pin is in Open/Drain Configuration DET pin is in Push/Pull Configuration
5	RES detection range setting	1	1: 10KΩ to 2560KΩ 0: 1KΩ to 256KΩ
4	GPIO control enable	1	1: Enable 0: Disable
3	Slow turn on control enable	1	1: Enable 0: Disable
2	MIC auto break out control enable	17	1: Enable 0: Disable
1	RES detection enable	01	Enable; will be changed to '0' after low resistance detection Disable
0	Audio jack detection and configuration enable	1	1: Enable; will be changed to '0' after audio jack detection and configuration 0: Disable

Table 21, RES DETECTION PIN SETTING

(Register 0x13h, Reset Value: 0x00, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:3	Reserved	5	Do not use
2:0	Pin Selection	3	000: CC_IN 001: DP_R 010: DN_L 011: SBU1 100: SBU2 101111: Do not use

Note: if RES detection pin is enable before setting PIN selection it will always do the CC_IN first. Recommend user to select the pin first before setting the RES detection pin enable.

Table 22, RES VALUE

(Register 0x14h, Reset Value: 0xFF, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:0	Detected resistance value	8	00000000: R < 1KΩ 11111111: R > 300KΩ



Table 23, RES DETECTION THRESHOLD

(Register 0x15h, Reset Value: 0x16, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:0	RES detection threshold	8	Selection by $1K\Omega$ per step if Register $12h[5] = 0$ Selection by $10K\Omega$ per step if Register $12h[5] = 1$ Default Value = $22K\Omega$ $00000000: 1K\Omega/10K\Omega$ $11111111: 256K\Omega/2560K\Omega$

Table 24, RES DETECTION INTERVAL

(Register 0x16h, Reset Value: 0x00, Type: Read/Write)

Ì	BITS	NAME	SIZE	DESCRIPTION
		INAIVIE	SIZE	DESCRIPTION
	7:2	Reserved	6	Do not use
	1:0	RES detection interval	2	00: Single 01: 100ms 10: 1s 11: 10s

Table 25, AUDIO JACK STATUS

(Register 0x17h, Reset Value: 0x01, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:4	Reserved	4	Do not use
3	4pole	1	1: 4 pole SBU2 to MIC, SBU1 to Audio Ground 0: others
2	4pole	1	1: 4 pole SBU1 to MIC, SBU2 to Audio Ground 0: others
1	3pole	1	1: 3 pole 0: others
0	No Audio Accessory	1	1: No Audio Accessory 0: Audio Accessory Attached

Table 26, RES DETETCTION/AUDIO JACK DETECTION INTERRUPT FLAG

(Register 0x18h, Reset Value: 0x00, Type: Read Clear)

(1 togictor	register extern, resect value: exect, type: read clear/					
BITS	NAME	SIZE	DESCRIPTION			
7:3	Reserved	5	Do not use			
2	Audio jack detection and configuration	1	1: Audio jack detection and configuration has not occurred 0: Audio jack detection and configuration has occurred			
1	Low resistance occurred	1	Low resistance has not occurred Example 1: Low resistance has occurred			
0	Low resistance detection	1	1: Low resistance detection has not occurred 0: Low resistance detection has occurred			

Table 27, RES DETETCTION /AUDIO JACK DETECTION INTERRUPT MASK

(Register 0x19h, Reset Value: 0x00, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:3	Reserved	5	Do not use
2	Audio jack detection and configuration	1	Mask Audio jack detection and configuration has occurred interrupt
1	Low resistance occurred	1	1: Low resistance has occurred interrupt
0	Low resistance detection	1	1:Low resistance detection has occurred interrupt

Table 28, AUDIO JACK DETECTION REG1 VALUE

(Register 0x1Ah, Reset Value: 0xFF, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:0	Audio jack detection value	8	Resistance between SBU1 to SBU2



Table 29, AUDIO JACK DETECTION REG2 VALUE

(Register 0x1Bh, Reset Value: 0xFF, Type: Read)

BITS	NAME	SIZE	DESCRIPTION
7:0	Audio jack detection value	8	Resistance between SBU2 to SBU1

Table 30, MIC DETECTION THRESHOLD DATA0

(Register 0x1Ch, Reset Value: 0x20, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:0	MIC detection threshold DATA0	8	MIC detection threshold DATA0 00100000: 300mV

Table 31, MIC DETECTION THRESHOLD DATA1

(Register 0x1Dh, Reset Value: 0xFF, Type: Read/Write)

1. 109.010.	extract range extra per reason		
BITS	NAME	SIZE	DESCRIPTION
7:0	MIC detection threshold DATA1	8	MIC detection threshold DATA1 11111111: 2400mV

Table 32, I2C RESET

(Register 0x1Eh, Reset Value: 0x00, Type: Write/Clear)

BITS	NAME	SIZE	DESCRIPTION
7:1	Reserved	7	Do not use
0	I2C Reset	1	0: default 1: I ² C reset

Table 33, CURRENT SOURCE SETTING

(Register 0x1Fh, Reset Value: 0x07, Type: Read/Write)

BITS	NAME	SIZE	DESCRIPTION
7:4	Reserved	4	Do not use
3:0	Current Source Setting	4	1111: 1500μA 0111: 700μA 0001: 100μA 0000: Invalid



TEST CIRCUITS

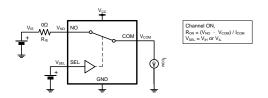


Figure 8, ON Resistance (Ron)

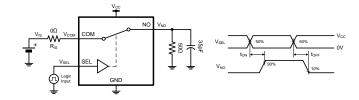


Figure 9, Turn-On and Turn-Off Time (ton/toff)

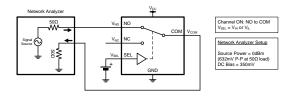


Figure 10, ON Channel -3dB Bandwidth (BW)

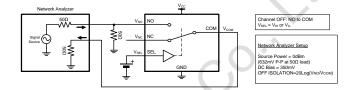
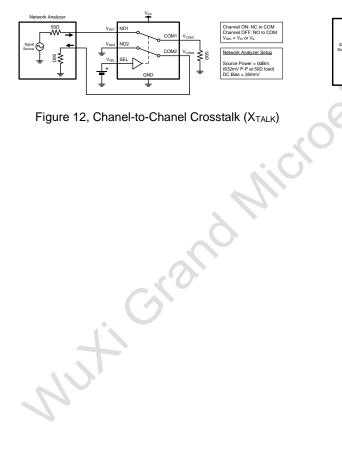


Figure 11, OFF Isolation (OISO)



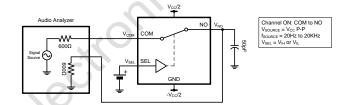
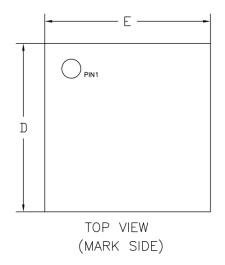
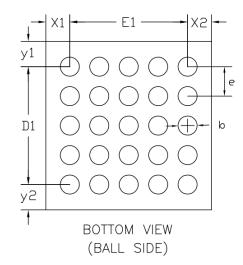


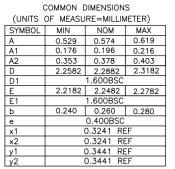
Figure 13, Total Harmonic Distortion (THD+N)



PACKAGE OUTLINE (CSP25-2.28x2.24)







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SIDE VIEW
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产品订购信息

器件编号	产品丝印	工作温度范围	封装信息	包装方法
ASW5480WLG	A80 YYWW ^(*)	-40°C 至 +85°C	WLCSP25-2.28x2.24	卷带和卷盘 (每卷 3000 只)

注: (*) YY 表示年号, WW 表示周号。